

/ Descriptions

PDFN5×6 N

N-Channel MOSFET in a PDFN5×6 Plastic Package.

/ Features

 $V_{DS}(V)=500V$ $I_D=1.7A$ $R_{DS(ON)}@10V \leq 3.5q$ (Typ. 2.8q)

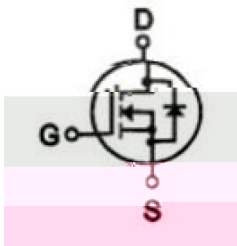
Fast Switching.

HF Product.

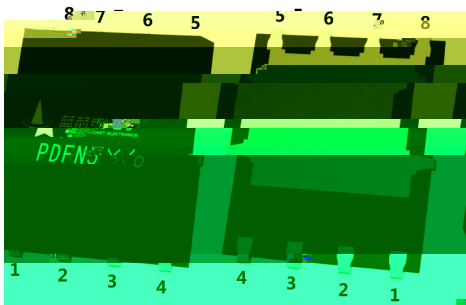
/ Applications

These devices are well suited for power switch circuit of adaptor and charger, intergrate fast recovery diode.

/ Equivalent Circuit



/ Pinning



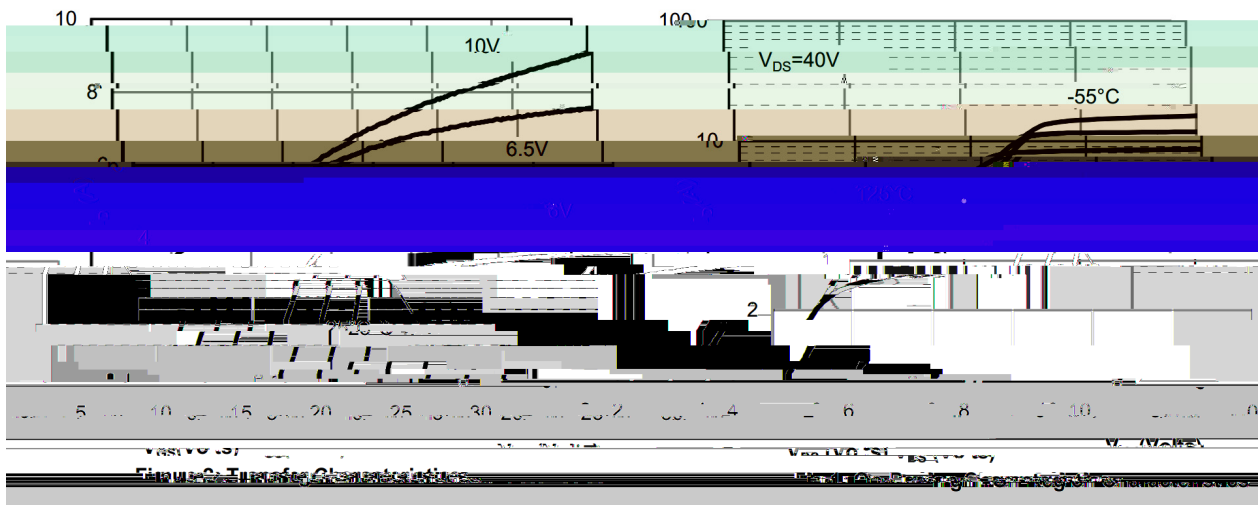
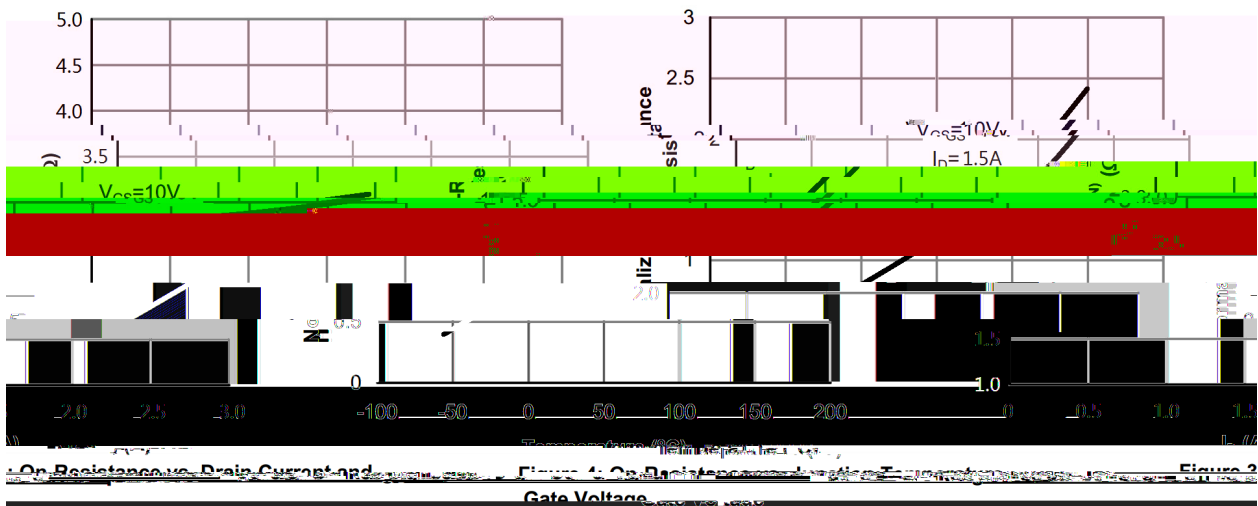
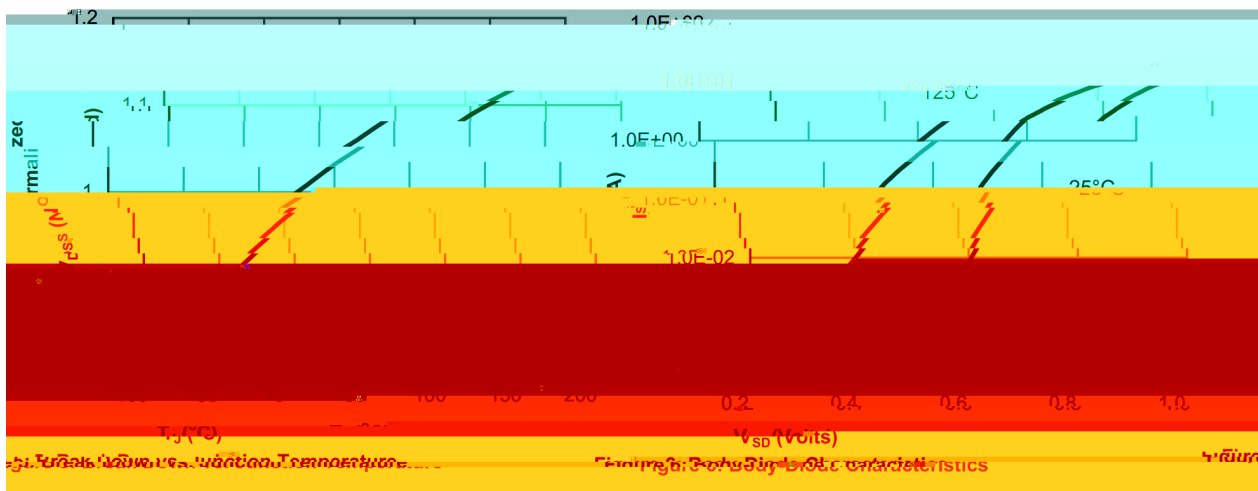
PIN1 2 3 S PIN4 G PIN5 6 7 8 D

/ Marking

See Marking Instructions.

Parameter	Symbol	Rating	Unit
Drain-Source Voltage	V_{DS}	500	V
Drain Current	$I_D(T_c=25\text{ }^{\circ}\text{C})$	1.7	A
Drain Current - Pulsed	I_{DM}	5.5	A
Gate-Source Voltage	V_{GS}	± 30	V
Single Pulsed Avalanche Energy	E_{AS}	112.5	mJ
Avalanche Current	I_{AS}		

/ Electrical Characteristic Curve



/ Electrical Characteristic Curve

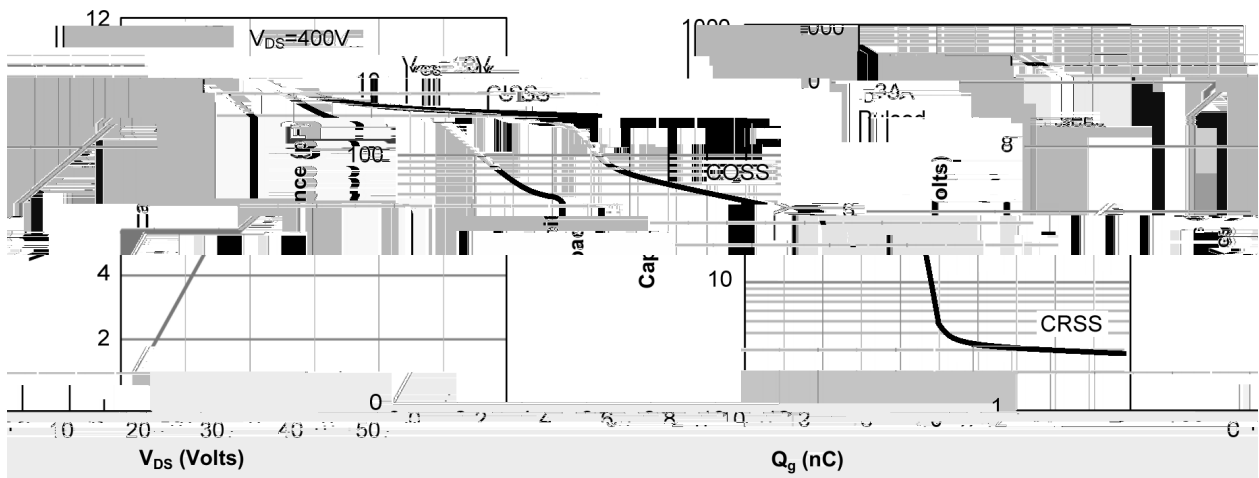


Figure 8: Capacitance Characteristics Figure 9: Gate Charge Characteristics

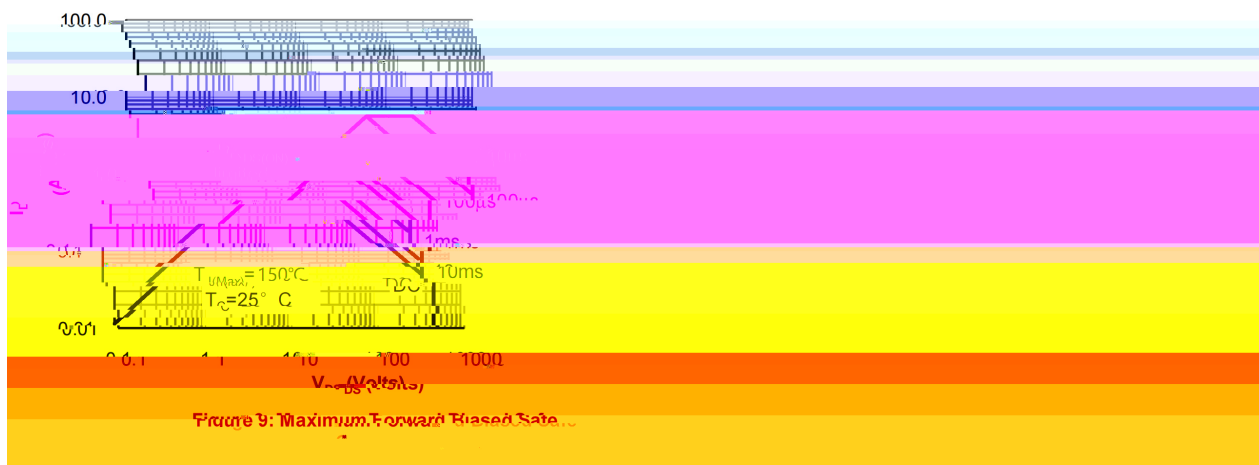


Figure 9: Maximum Forward Biased Safe Area

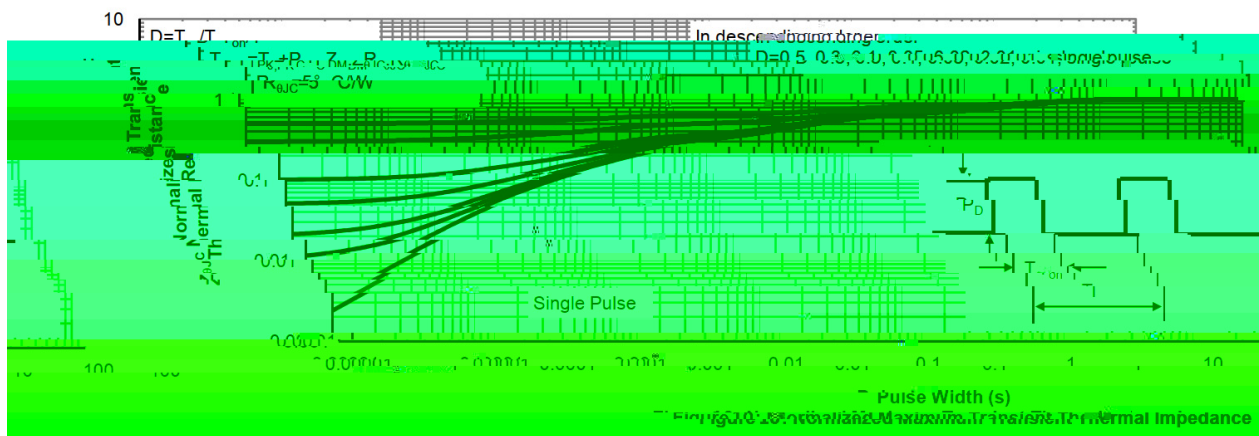
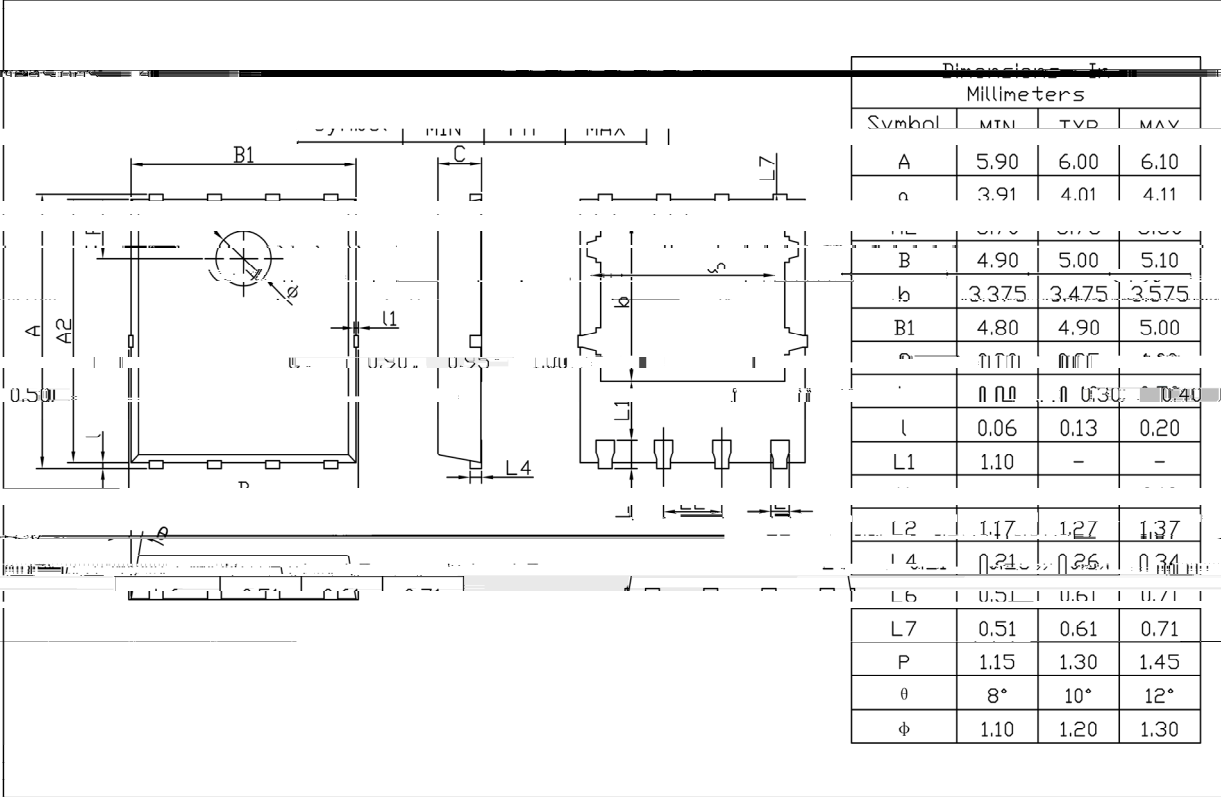


Figure 10: Single Pulse Thermal Impedance

I Package Dimensions

PDFN5 X6Unit:mm



Rev.01 202209

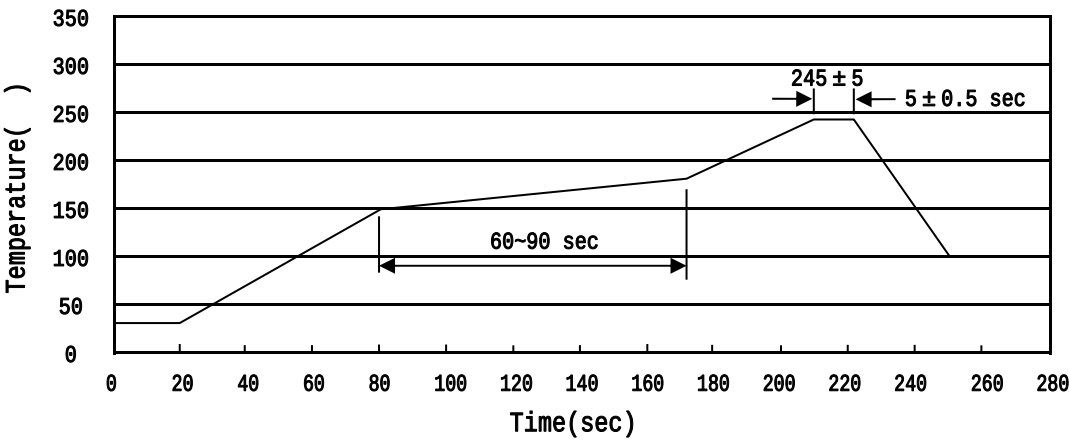
/ Marking Instructions



BR
3N50AF

Note	
BR	Company Code
3N50AF	Product Type Code
****	Lot No. Code, code change with Lot No

() / Temperature Profile for IR Reflow Soldering(Pb-Free)



Note:

- 1

150 180

60 90sec;

1.Preheating:150~180 , Time:60~90sec.
- 2

245±5

5±0.5sec;

2.Peak Temp.:245±5 , Duration:5±0.5sec.
- 3

2 10 /sec.

3. Cooling Speed: 2~10 /sec.

/ Resistance to Soldering Heat Test Conditions

260±5 10±1 sec. Temp.:260±5 Time:10±1 sec

/ Packaging SPEC.

/ REEL

Package Type	Units					Dimension (unit ㎜ mm ³)		
	Units/Reel /	Reels/Inner Box /	Units/Inner Box /	Inner Boxes/Outer Box /	Units/Outer Box /	Reel	Inner Box	Outer Box
PDFN5×6	5,000	2	10,000	6	60,000	13"×12	360×360×50	380×335×366

/ Notices